



Material Content Data Sheet



Sales Product Name		TLE6254-3G		Issued		25. January 2018		
MA#		MA001724244						
Package		PG-DSO-14-1		Weight*		144.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.050	4.89	4.89	48934	48934
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		419	
	non noble metal	iron	7439-89-6	1.207	0.84		8377	
wire	non noble metal	copper	7440-50-8	49.007	34.02	34.91	340157	349058
	noble metal	gold	7440-57-5	0.247	0.17	0.17	1713	1713
	encapsulation	organic material	carbon black	1333-86-4	0.164	0.11		1136
encapsulation	plastics	epoxy resin	-	7.530	5.23		52267	
	inorganic material	silicondioxide	60676-86-0	74.156	51.48	56.82	514720	568123
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8511	8511
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7148	7148
glue	plastics	acrylic resin	-	0.523	0.36		3633	
	noble metal	silver	7440-22-4	1.856	1.29	1.65	12880	16513
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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